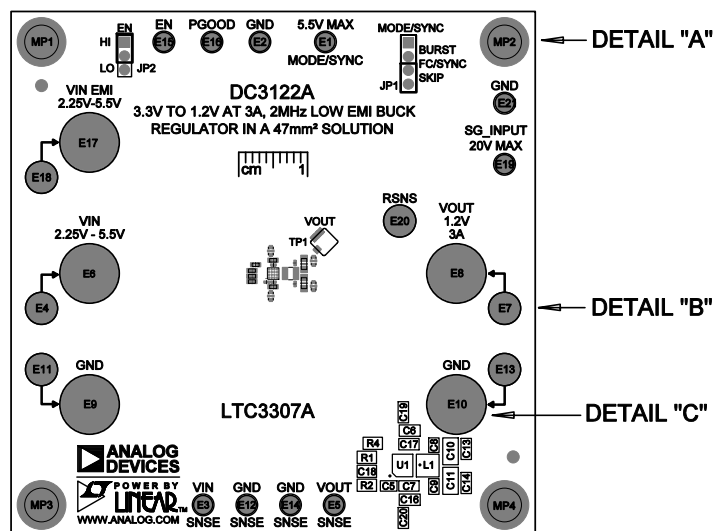
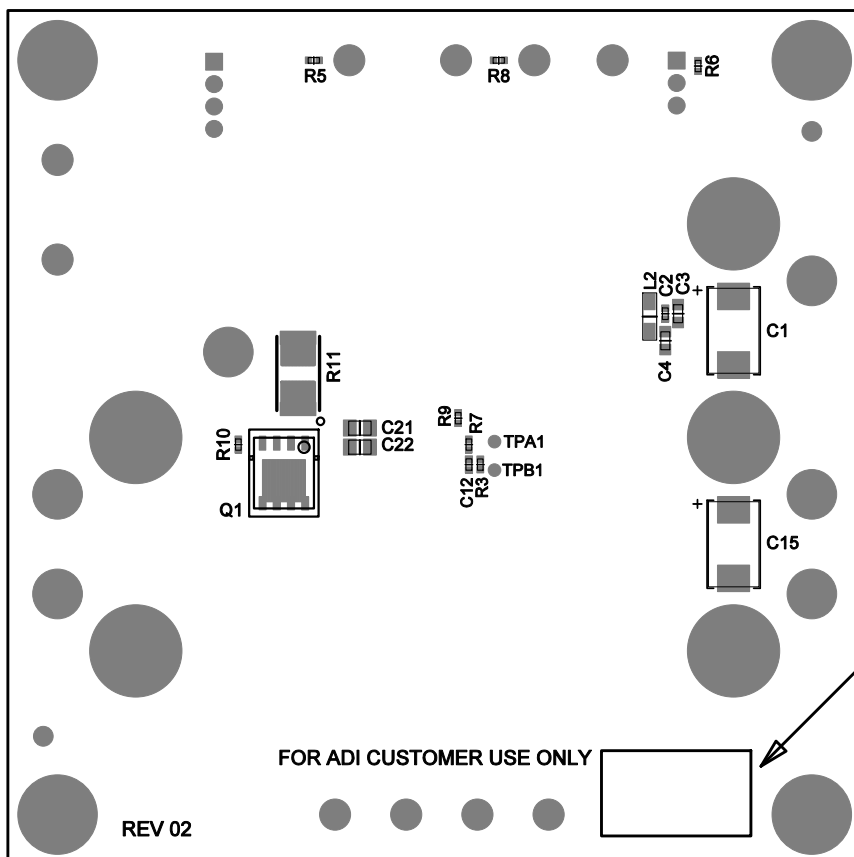




REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	02	PRODUCTION	MM	08-04-21

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.





APPROVALS		  FOR ADI CUSTOMER USE ONLY	
PCB DES.	NC	TITLE: BOTTOM ASSEMBLY DRAWING 3.3V TO 1.2V AT 3A, 2MHz LOW EMI BUCK REGULATOR IN A 47mm ² SOLUTION	
APP ENG.	MM		
SCALE = NONE		SIZE N/A	IC NO. LTC3307A DEMO CIRCUIT 3122A
		REV 02	
		SHT 2 of 2	